

Title (en)  
ELECTROPLATING DEVICE AND METHOD

Title (de)  
VORRICHTUNG UND VERFAHREN ZUR GALVANISCHEN BESCHICHTUNG

Title (fr)  
DISPOSITIF ET PROCÉDÉ DE REVÊTEMENT GALVANIQUE

Publication  
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Application  
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Abstract (en)  
[origin: WO2007118875A2] The invention relates to a device for electroplating at least one electrically conductive substrate (8), or an electrically conductive structure situated on a non-conductive substrate (8). Said device comprises at least one bath, an anode and a cathode (2). The bath contains an electrolyte solution, which comprises at least one metal salt and from which metal ions are deposited on electrically conductive surfaces of the substrate, as the cathode is brought into contact with the surface of the substrate to be coated and said substrate is conveyed through the bath. The cathode comprises at least one strip (2) with at least one electrically conductive segment (12) and is guided around at least two rotating shafts (3). The invention also relates to a method for electroplating at least one substrate that is carried out in a device according to the invention. According to said method, to produce the coating, the strip lies on the substrate and circulates at a speed corresponding to the speed at which the substrate is conveyed through the bath. The invention further relates to the use of said device for electroplating electrically conductive structures situated on an electrically non-conductive support.

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